

Document Receipt Acknowledgement

Date:
Section:
Name:



Document Number: D09809-A-K1561

Date: July.,30, 2026

Attention:

TTI ELECTRONICS ASIA PTE LTD**4M Change Notice**

Resin Molding SMD Type Ceramic Capacitors DK1 Series

Dear. Valued Customer

Thank you very much for your great and continued support for business with Murata.
This is the official notification that some of our products' 4M Change will be proceeded as detailed below.
Please review this, and confirm that you will expect to receive products after this 4M Change.
Your understanding and support are highly appreciated.

1. Product Type, Changes, and Customer/Murata/Alternative Part Numbers:

Product Type: Resin Molding SMD Type Ceramic Capacitors DK1 Series

Changes: ☐ Man ☐ Machine ☒ Material ☐ Method

Before Change	After Change
Halogen-containing HIC	Halogen-free HIC
Current label information	New label information

Please refer to the attached documents for detailed Part Numbers' information.

2. Reasons/Background:

In response to market demand for halogen-free (hereinafter "HF") products,
we are working to transition our packaging materials to HF as well.
Since the HIC (Humidity Indicator Card) included with the packaging of the affected products
contains halogens, we will be switching to an HF HIC.

3. Products Before and After the Change:

This change applies only to the HIC, there are no changes to the product itself.
Therefore, this change will not affect the product's quality, specifications, or any other aspects.
Please note that some product specifications may include references to the HIC; however,
unless there are specific requests, we will not revise the product specifications.

4. Change Schedule:

Production Start in New HIC: Apr., 01, 2027
Last Shipment Date in Current HIC: Jun., 30, 2027
We will begin shipping products with the updated HIC in due course.

5. Contact Window:

Should you have any questions or concerns,
please contact Murata Sales, Representative, or Distributor in your area.

6. Request regarding information handling

We kindly request that the information provided by us not be disclosed or
shared with third parties, including data base providers or by posting on websites.

Truly Yours. Thank you.

Izumo Murata Manufacturing, Co., Ltd.
Product Engineering Sec.5
Senior Manager : Makoto Kashiwai

Part Number List

Please find the list below for the target part numbers which are registered as yours in Murat
Regardless of the list below, all part numbers shall be the target as far as they are categoriz

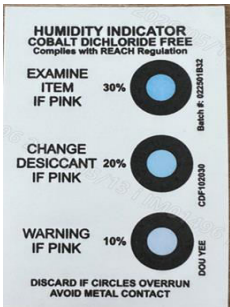
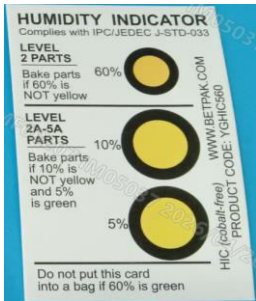
Customer Part Number	Murata Part Number	Alternative Part Number
DK1B3EA101K86RBH01	DK1B3EA101K86RBH01	-
DK1B3EA681K86RBH01	DK1B3EA681K86RBH01	-
DK1E3EA102M86RAH01	DK1E3EA102M86RAH01	-
DK1E3EA102M86RBH01	DK1E3EA102M86RBH01	-
DK1E3EA152M86RAH01	DK1E3EA152M86RAH01	-
DK1E3EA152M86RBH01	DK1E3EA152M86RBH01	-

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a. (Customer Part Number)
zed into the Product Type indicated in the Document.

Changes

HIC

Current	New
	

As shown in the photo above, we will be updating the HIC.
Due to the HIC update, some text and colors will change as shown above.

The color changes will be as follows:
Current: Blue ⇒ Pink
New: Yellow ⇒ Green

Changes

Label

Current (現行)

	Caution This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL (MSL) 3
	1. Calculated shelf life in sealed bag: 24 months at < 30 °C and < 60% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature: 260 °C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30 °C / 60% RH, or b) Stored per J-STD-033 4. Devices require bake, before mounting, if the humidity indicator spot of 10% changes from blue to pink. 5. If baking is required, perform baking (60 °C x 168 hr) before soldering. Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J-STD-020	

New (新)

	Caution This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL (MSL) 3
	1. Calculated shelf life in sealed bag: 24 months at < 30 °C and < 60% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature: 260 °C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30 °C / 60% RH, or b) Stored per J-STD-033 4. Devices require bake, before mounting, if the HIC (humidity indicator card) indicates a level exceeding 10%. 5. If baking is required, perform baking (60 °C x 168 hr) before soldering. Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J-STD-020	